

A<sup>4</sup> spaced from the hot plate--;

line 14, after "material" insert --coating liquid--;

line 15, after "treated" insert --W--.

BEST AVAILABLE C.

after line 21, insert the following paragraph

A<sup>5</sup> --Although there have been described in detail what are the present embodiments of the invention, it will be understood by persons skilled in the art that variations and modifications may be made thereto without departing from the gist, spirit or essence of the invention. The scope of the invention is indicated by the appended claims.

IN THE CLAIMS:

Please amend the claims as follows.

- AG SUB C. 1
- 1 (amended) A method for forming a coating film, comprising the [following]  
2 steps of:  
3 applying a raw material of a low dielectric constant onto a surface of a plate-like  
4 material to be treated [such as a semiconductor wafer and a glass substrate];  
5 reducing [the] oxygen concentration in the atmosphere surrounding the plate-  
6 like material to be less than or equal to 1% before [the] a surface temperature of said  
7 plate-like material to be treated rises to 200°C; thereafter  
8 heating said plate-like material to be treated to [be] a temperature greater than  
9 or equal to 400°C; and then  
10 maintaining the oxygen content in the atmosphere to be less than or equal to

11 1% until the surface temperature of said plate-like material to be treated lowers to  
 12 200°C.

Claim 2, line 2, after "purging" insert --with--.

1 A? 3. (amended) A method for forming a coating film as defined in claim 1, wherein  
 2 said method is conducted in one baking furnace, [in the upper portion of which is  
 3 positioned a hot plate, while in the lower portion of which is positioned a cool plate,  
 4 in which said plate-like material to be treated comes close to either one of said hot  
 5 plate and said cool plate selectively by means of an elevator means] the baking  
 6 furnace including a hot plate and a cool plate vertically spaced from each other, and  
 7 elevator means for selectively moving the plate-like material to be treated relative to  
 8 the hot and cool plates, to thereby control the surface temperature of the plate-like  
 9 material.

1 SUB B5 > 4. (Amended) A method for forming a coating film as defined in [any one of  
 2 claims] claim 1 [through 3], wherein said method [is applied to a] involves forming of  
 3 an interlayer insulation film by a damascene method.

Please add the following new claims.

1 A<sup>5</sup> SUB B<sup>6</sup> > 5. (new) A method for forming a coating film as defined in claim 2, wherein said  
 2 method involves forming of an interlayer insulation film by a damascene method.

1 6. (new) A method for forming a coating film as defined in claim 3, wherein said  
 2 method involves forming of an interlayer insulation film by a damascene method.

1 7. (new) A method for forming a coating film as defined in claim 3, wherein said